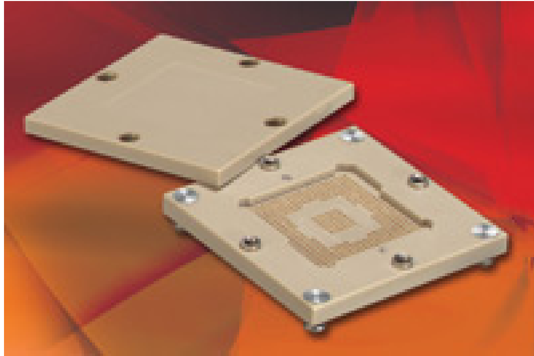
BallNest Hybrid Socket Provides Reliable, Consistent Test and Burn-in



Aries Electronics has released its patented CSP/BallNest Hybrid Socket suitable for prototyping, test or burn-in of CSP (chip scale package), BGA (ball grid array), microBGA and LGA (land grid array) devices. The socket, which features a lid that nests each ball termination into the socket for a reliable connection, can be used on any device with a 0.30 mm pitch or larger. The ZIF-style (zero insertion force) socket uses Aries solderless, gold-plated pressure mount spring probes, allowing for easy mounting and removal from the PCB (printed circuit board). The design maintains constant force throughout the entire test and burn-in cycle as well as on the surface mount PCB when no chip is engaged. The socket bolts down onto the target PCB in the same footprint as the socketed device. This process also enables the socket to be mounted to an adapter board terminated with male thru-pins effectively creating a thru-hole solder tail socket for BGA devices. With a signal path of only 0.077 inches (1.96 mm), this socket provides minimal signal loss for higher bandwidth capability.

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